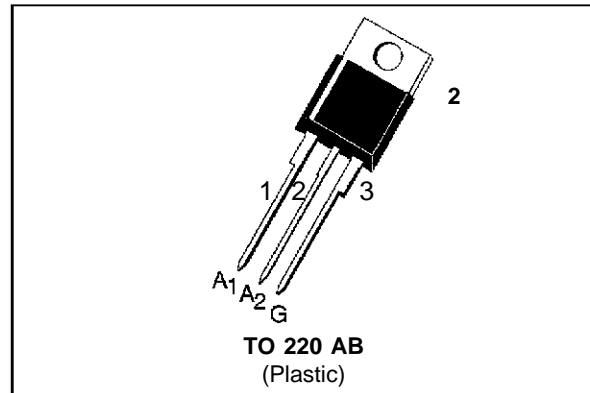


## REVERSED BATTERY AND OVERVOLTAGE PROTECTION CIRCUIT (RBO)

PRELIMINARY DATA

### FEATURES

- DISSIPATION THROUGH PIN 2 : TAB CONNECTED TO GROUND
- MONOLITHIC SILICON CHIP
- NEGATIVE OVERVOLTAGE PROTECTION BY CLAMPING (COMPONENT T1)
- BREAKDOWN VOLTAGE : 24 V min
- CLAMPING VOLTAGE :  $\pm 40$  V max
- AVERAGE FORWARD CURRENT (COMPONENT D1) : 40 A



### DESCRIPTION

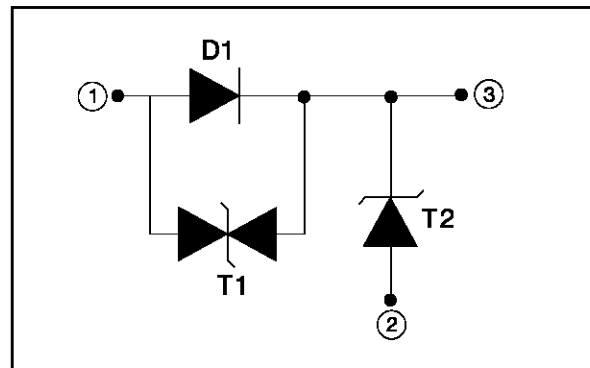
Developed especially for automotive reversed battery operation and overvoltage (load dump) protection, this monolithic component chip offers multiple functions in the same package (see page 4) :

D1 : reversed battery protection

T1 : clamping function to negative overvoltage effect

T2 : Transil function to Load Dump effect

### FUNCTIONAL DIAGRAM



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
I <sub>FSM</sub>	Non repetitive surge peak forward current between Pins 1 and 3 @ T= 10 $\mu$ s	T <sub>j</sub> = 25°C	400	A
I <sub>F(AV)</sub>	Average forward current between Pins 1 and 3	T <sub>c</sub> = 80°C	40	A
V <sub>PP</sub>	Peak load dump voltage (see note 1 and 2)	T <sub>c</sub> = 85°C	80	V
P <sub>PP</sub>	Peak pulse power between Pins 1 and 3 @ T= 1 ms	T <sub>c</sub> = 85°C	1500	W
P	Total power dissipation	T <sub>c</sub> = 80°C	70	W
T <sub>stg</sub> T <sub>j</sub>	Storage and junction temperature range		- 40 to + 150	°C
T <sub>L</sub>	Maximum lead temperature for soldering during 10 s at 4.5 mm from case		230	°C

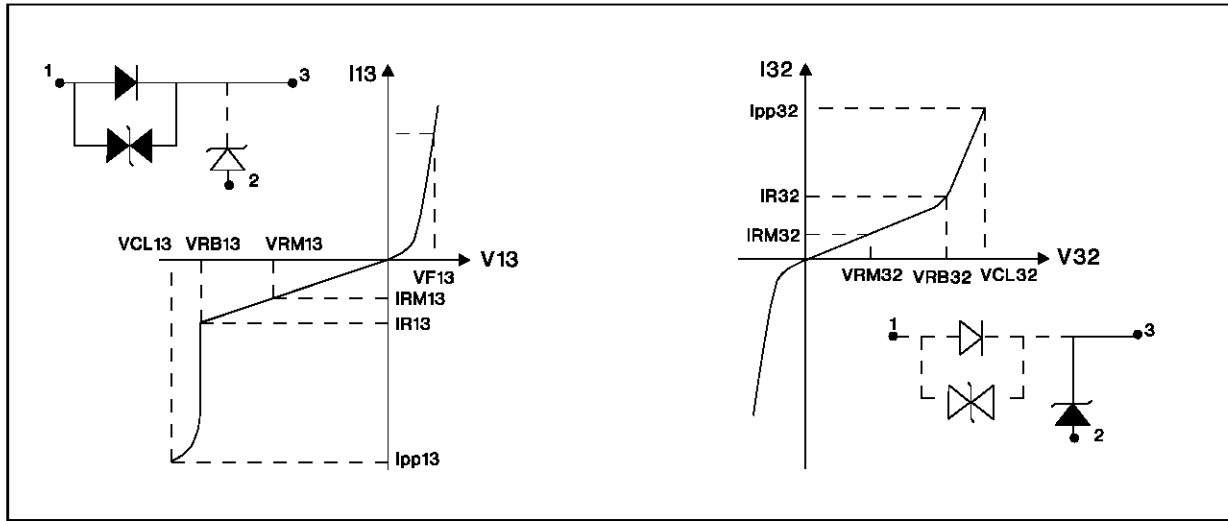
**Notes 1** : for a surge greater than the maximum value, the source will present a short circuit.

**Notes 2** : see schaffner circuit page 3

# RBO40-40

## THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
Rth (j-c)	Junction to case	1	°C/W



## ELECTRICAL CHARACTERISTICS

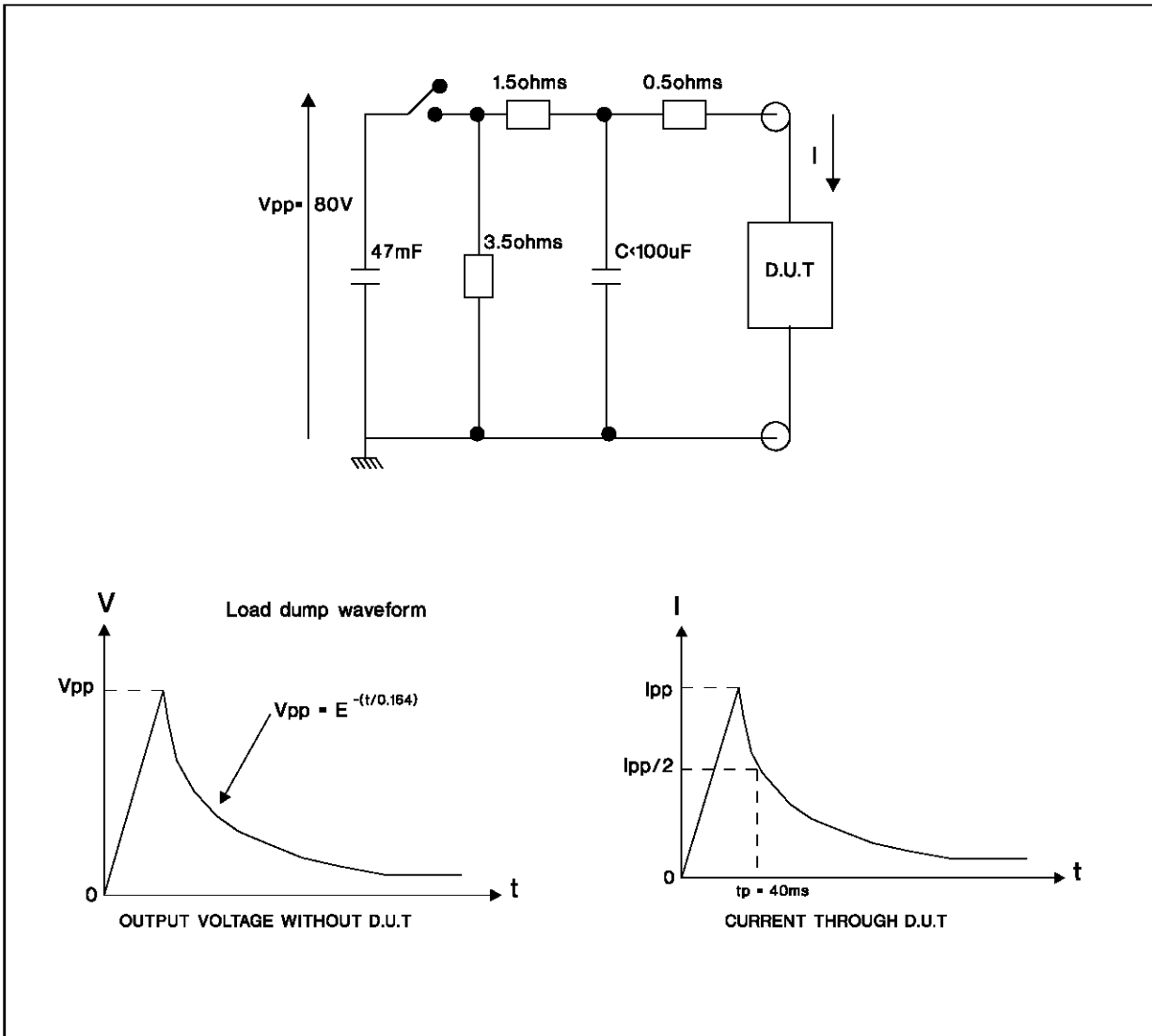
Symbol	Test Conditions			Value	Unit
$V_F 13$	Maximum forward voltage @ $I_F = 40 \text{ A}$	$T_j = 25^\circ\text{C}$	MAX	1.7	V
		$T_j = 85^\circ\text{C}$			
$V_F 13$	Maximum forward voltage @ $I_F = 20 \text{ A}$	$T_j = 25^\circ\text{C}$	MAX	1.35	V
		$T_j = 85^\circ\text{C}$			
$V_F 13$	Maximum forward voltage @ $I_F = 1 \text{ A}$	$T_j = 85^\circ\text{C}$	MAX	0.9	V
$V_{BR} 31$	Breakdown voltage @ $I_R = 1 \text{ mA}$	$T_j = 25^\circ\text{C}$	MIN	24	V
			MAX	32	
$I_{RM} 31$	Leakage current @ $V_{RM} = 20 \text{ V}$	$T_c = 25^\circ\text{C}$	MAX	50	$\mu\text{A}$
		$T_c = 85^\circ\text{C}$		300	
$V_{CL} 31$	Clamping voltage @ $I_{PP} = 37.5 \text{ A}$ @ $T = 1 \text{ ms}$	$T_c = 25^\circ\text{C}$	MAX	40	V
$V_{BR} 32$	Breakdown voltage @ $I_R = 1 \text{ mA}$	$T_j = 25^\circ\text{C}$	MIN	24	V
			MAX	32	
$I_{RM} 32$	Leakage current @ $V_{RM} = 20 \text{ V}$	$T_c = 25^\circ\text{C}$	MAX	10	$\mu\text{A}$
		$T_c = 85^\circ\text{C}$		100	
$V_{CL} 32$	Clamping voltage @ $I_{PP} = 20 \text{ A}$	$T_c = 25^\circ\text{C}$	MAX	40	V
$\alpha t$	Temperature coefficient	$T_c = 25^\circ\text{C}$	MAX	10-4	$^\circ\text{C}$
$C 13$	Capacitance at 0 V	$T_c = 25^\circ\text{C}$	TYP	3000	pF
$C 32$	Capacitance at 0 V	$T_c = 25^\circ\text{C}$	TYP	7000	pF

Note : 13 and 32

Ex :  $V_F 13$  . between Pin 1 and Pin 3

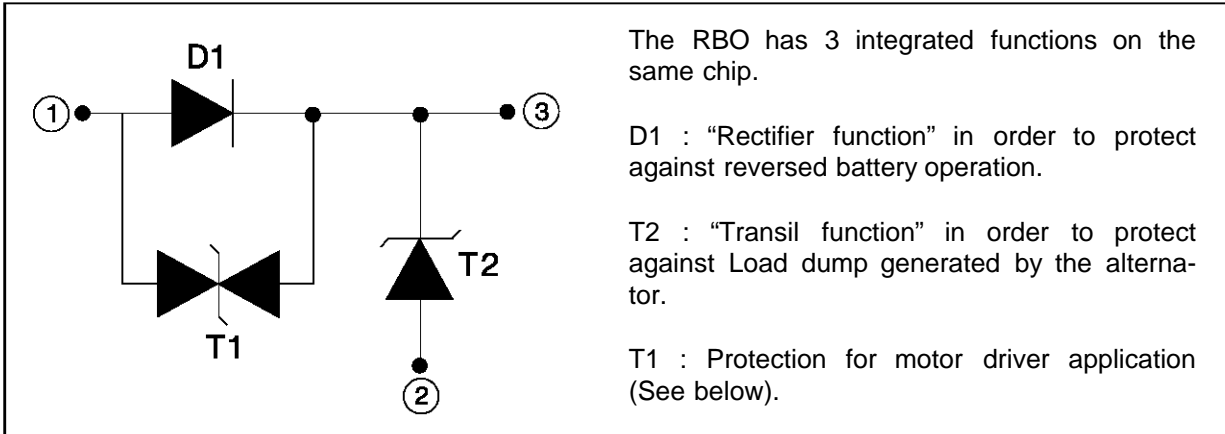
$V_{BR} 32$  . between Pin 3 and Pin 2

SCHAFFNER CIRCUIT

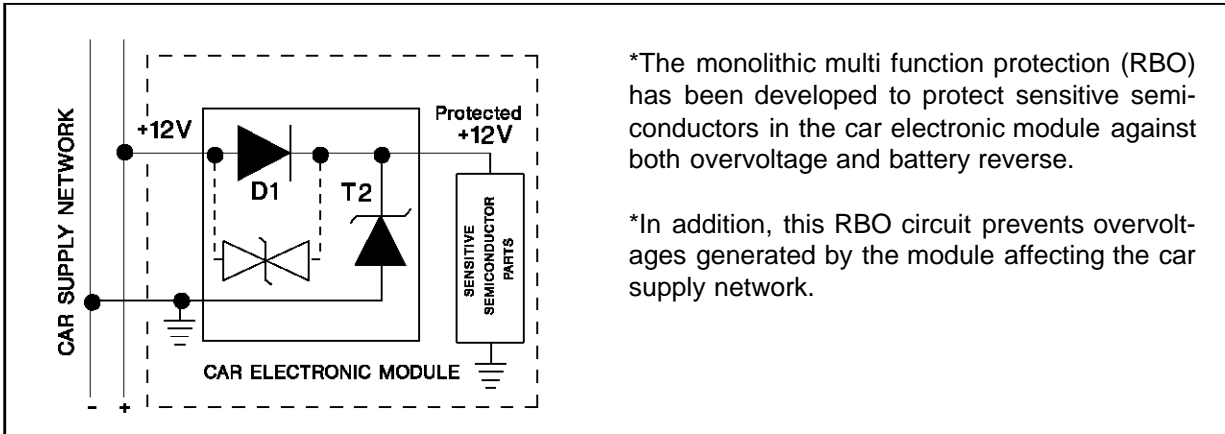


## RBO40-40

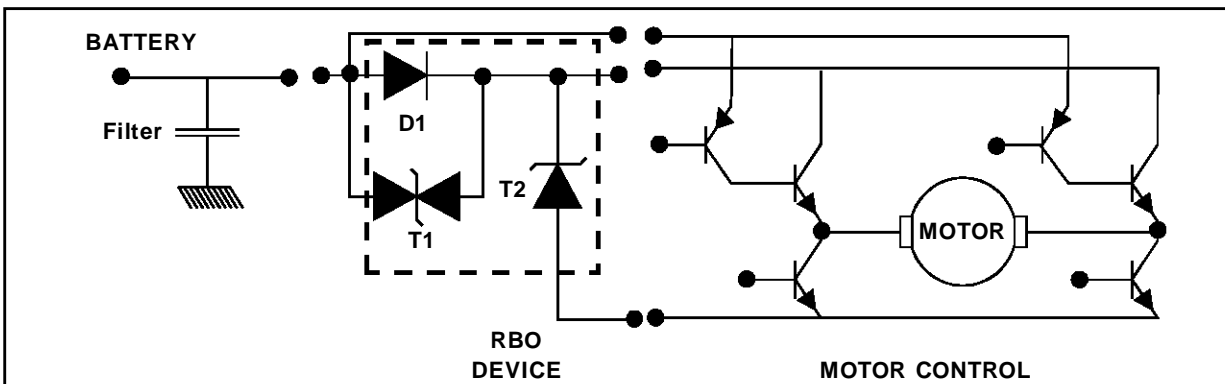
### PRODUCT DESCRIPTION



### BASIC APPLICATION



### MOTOR DRIVER APPLICATION



In this application, one half of the motor drive circuit is supplied through the "RBO" and is thus protected as per its basic function application.

The second part is connected directly to the "car supply network" and is protected as follows :

- For positive surges : T2 (clamping phase) and D1 forward-biased.
- For negative surges : T1 (clamping phase) and T2 forward-biased.



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